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Maxim Integrated MAX9986AETP+

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19-3906: Rev 0: 1/06





# SiGe High-Linearity, 815MHz to 1000MHz **Downconversion Mixer with LO Buffer/Switch**

#### **General Description**

The MAX9986A high-linearity downconversion mixer provides 8.2dB gain, +25dBm IIP3, and 10dB NF for 815MHz to 1000MHz base-station receiver applications. With a 960MHz to 1180MHz LO frequency range, this particular mixer is ideal for high-side LO injection receiver architectures. Low-side LO injection is supported by the MAX9984, which is pin-for-pin and functionally compatible with the MAX9986A.

In addition to offering excellent linearity and noise performance, the MAX9986A also yields a high level of component integration. This device includes a double-balanced passive mixer core, an IF amplifier, a dual-input LO selectable switch, and an LO buffer. On-chip baluns are also integrated to allow for single-ended RF and LO inputs. The MAX9986A requires a nominal LO drive of 0dBm, and supply current is guaranteed to be below 250mA.

The MAX9986A is a derivative version of the MAX9986 with improved large-signal blocking performance. The MAX9984/MAX9986/MAX9986A are pin compatible with the MAX9994/MAX9996 1700MHz to 3000MHz mixers, making this entire family of downconverters ideal for applications where a common PC board layout is used for both frequency bands. The MAX9986A is also functionally compatible with the MAX9993.

The MAX9986A is available in a compact, 20-pin, thin QFN package (5mm x 5mm) with an exposed paddle. Electrical performance is guaranteed over the extended -40°C to +85°C temperature range.

#### **Applications**

850MHz WCDMA Base Stations

GSM 850/GSM 900 2G and 2.5G EDGE Base Stations

cdmaOne™ and cdma2000® Base Stations

iDEN® Base Stations

Predistortion Receivers

Fixed Broadband Wireless Access

Wireless Local Loops

Private Mobile Radios

Military Systems

Microwave Links

Digital and Spread-Spectrum Communication Systems

cdma2000 is a registered trademark of the Telecommunications Industry Association.

cdmaOne is a trademark of CDMA Development Group. iDEN is a registered trademark of Motorola, Inc.

## ♦ 815MHz to 1000MHz RF Frequency Range

- 960MHz to 1180MHz LO Frequency Range (MAX9986A/MAX9986)
- ◆ 570MHz to 850MHz LO Frequency Range (MAX9984)
- ♦ 50MHz to 250MHz IF Frequency Range
- ♦ 8.2dB Conversion Gain
- ♦ +25dBm Input IP3
- ♦ +14.8dBm Input 1dB Compression Point
- ♦ 10dB Noise Figure
- ♦ 69dBc 2LO 2RF Spurious Rejection at PRF = -10dBm
- ♦ Integrated LO Buffer
- Integrated RF and LO Baluns for Single-Ended Inputs
- ♦ Low -3dBm to +3dBm LO Drive
- ♦ Built-In SPDT LO Switch with 49dB LO1 to LO2 Isolation and 50ns Switching Time
- ♦ Pin Compatible with MAX9994/MAX9996 1700MHz to 3000MHz Mixers
- Functionally Compatible with MAX9993
- ♦ External Current-Setting Resistors Provide Option for Operating Mixer in Reduced Power/Reduced **Performance Mode**
- Lead-Free Package Available

#### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE	PKG CODE
MAX9986AETP	-40°C to +85°C	20 Thin QFN-EP* 5mm × 5mm	T2055-3
MAX9986AETP-T	-40°C to +85°C	20 Thin QFN-EP* 5mm × 5mm	T2055-3
MAX9986AETP+	-40°C to +85°C	20 Thin QFN-EP* 5mm × 5mm	T2055-3
MAX9986AETP+T	-40°C to +85°C	20 Thin QFN-EP* 5mm × 5mm	T2055-3

<sup>\*</sup>EP = Exposed paddle.

Pin Configuration/Functional Diagram and Typical Application Circuit appear at end of data sheet.

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<sup>+ =</sup> Lead free.

T = Tape-and-reel.



#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND0.3V to +5.5V
IF+, IF-, LOBIAS, LOSEL, IFBIAS to GND0.3V to (V <sub>CC</sub> + 0.3V)
TAP0.3V to +1.4V
LO1, LO2, LEXT to GND0.3V to +0.3V
RF, LO1, LO2 Input Power+12dBm
RF (RF is DC shorted to GND through a balun)50mA
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
20-Pin Thin QFN-EP (derate 26.3mW/°C above +70°C)2.1W

θJA	+38°C/W
θJC	
Operating Temperature Range (Note A)TC	$= -40^{\circ}$ C to $+85^{\circ}$ C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Note A: T<sub>C</sub> is the temperature on the exposed paddle of the package.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

(MAX9986A Typical Application Circuit,  $V_{CC}$  = +4.75V to +5.25V, no RF signal applied, IF+ and IF- outputs pulled up to  $V_{CC}$  through inductive chokes, R1 = 953 $\Omega$ , R2 = 619 $\Omega$ , T<sub>C</sub> = -40°C to +85°C, unless otherwise noted. Typical values are at  $V_{CC}$  = +5V, T<sub>C</sub> = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage	Vcc		4.75	5.00	5.25	V
Supply Current	Icc			213	250	mA
LO_SEL Input-Logic Low	V <sub>IL</sub>				8.0	V
LO_SEL Input-Logic High	VIH		2			V

#### **AC ELECTRICAL CHARACTERISTICS**

(MAX9986A Typical Application Circuit,  $V_{CC}$  = +4.75V to +5.25V, RF and LO ports are driven from 50Ω sources,  $P_{LO}$  = -3dBm to +3dBm,  $P_{RF}$  = -5dBm,  $f_{RF}$  = 815MHz to 1000MHz,  $f_{LO}$  = 960MHz to 1180MHz,  $f_{IF}$  = 160MHz,  $f_{LO}$  >  $f_{RF}$ ,  $f_{CC}$  = -40°C to +85°C, unless otherwise noted. Typical values are at  $V_{CC}$  = +5V,  $P_{RF}$  = -5dBm,  $P_{LO}$  = 0dBm,  $f_{RF}$  = 910MHz,  $f_{LO}$  = 1070MHz,  $f_{IF}$  = 160MHz,  $f_{CC}$  = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS		
RF Frequency Range	f <sub>RF</sub>	(Note 2)	815		1000	MHz		
LO Fraguenay Panga	f. o	(Note 2)	960		1180	MHz		
LO Frequency Range	fLO	MAX9984	570		850	IVI□Z		
IF Frequency Range	fIF	(Note 2)	50		250	MHz		
Conversion Gain	GC	$T_C = +25^{\circ}C$	7.2	8.2	9.3	dB		
Gain Variation Over Temperature		$T_C = -40$ °C to $+85$ °C		-0.009		dB/°C		
Conversion Gain Flatness		Flatness over any one of three frequency bands: f <sub>RF</sub> = 824MHz to 849MHz f <sub>RF</sub> = 869MHz to 894MHz f <sub>RF</sub> = 880MHz to 915MHz		±0.15		dB		
Input Compression Point	P <sub>1dB</sub>	(Note 3)	14.8 dBm					
Input Third-Order Intercept Point IIP3		Two tones: $f_{RF1} = 910MHz$ , $f_{RF2} = 911MHz$ , $P_{RF} = -5dBm/tone$ , $f_{LO} = 1070MHz$ , $P_{LO} = 0dBm$ , $T_{A} = +25^{\circ}C$	22	25		dBm		
Input IP3 Variation Over		$T_C = +25$ °C to -40°C		-1.8		٩D		
Temperature		$T_C = +25^{\circ}C \text{ to } +85^{\circ}C$		+0.7		dB		



### AC ELECTRICAL CHARACTERISTICS (continued)

 $(\text{MAX9986A Typical Application Circuit}, \ V_{CC} = +4.75 \text{V to } +5.25 \text{V}, \ \text{RF and LO ports are driven from } 50 \Omega \ \text{sources}, \ P_{LO} = -3 \text{dBm to } +3 \text{dBm}, \ P_{RF} = -5 \text{dBm}, \ f_{RF} = 815 \text{MHz to } 1000 \text{MHz}, \ f_{LO} = 960 \text{MHz to } 1180 \text{MHz}, \ f_{IF} = 160 \text{MHz}, \ f_{LO} > f_{RF}, \ T_{C} = -40 ^{\circ} \text{C to } +85 ^{\circ} \text{C}, \ \text{unless otherwise noted}. \ Typical \ values \ \text{are at } V_{CC} = +5 \text{V}, \ P_{RF} = -5 \text{dBm}, \ P_{LO} = 0 \text{dBm}, \ f_{RF} = 910 \text{MHz}, \ f_{LO} = 1070 \text{MHz}, \ f_{IF} = 160 \text{MHz}, \ T_{C} = +25 ^{\circ} \text{C}, \ \text{unless otherwise noted}.) \ (\text{Note 1})$ 

PARAMETER	SYMBOL	CONDITIO	NS	MIN	TYP	MAX	UNITS
Noise Figure	NF	Single sideband, f <sub>IF</sub> = 190	)MHz		10		dB
Noise Figure Under Blocking		$f_{RF} = 900MHz$ (no signal) $f_{LO} = 1090MHz$	PBLOCKER = +8dBm		20		dB
Noise Figure Under-Blocking		fBLOCKER = 981MHz fIF = 190MHz (Note 4)	PBLOCKER = +11dBm		23		ив
Small-Signal Compression		PFUNDAMENTAL = -5dBm fFUNDAMENTAL = 910MHz	PBLOCKER = +8dBm		0.18		dB
Under-Blocking Condition		fBLOCKER = 911MHz	P <sub>BLOCKER</sub> = +11dBm		0.4		ив
LO Drive				-3		+3	dBm
	2 x 2	2LO - 2RF	$P_{RF} = -10dBm$		69		
Spurious Response at IF	2 / 2	20-2111	$P_{RF} = -5dBm$		64		dBc
Spurious response at ii	3 x 3	3LO - 3RF	$P_{RF} = -10dBm$		88		abc
	0 / 0	P	$P_{RF} = -5dBm$		78		
LO1-to-LO2 Isolation		$P_{LO} = +3dBm$	LO2 selected	42	49		dB
Lot to Edz fooldfor		$T_C = +25^{\circ}C \text{ (Note 5)}$	LO1 selected	42	50		GB
LO Leakage at RF Port		$P_{LO} = +3dBm$			-45		dBm
LO Leakage at IF Port		$P_{LO} = +3dBm$			-33		dBm
RF-to-IF Isolation					54		dB
LO Switching Time		50% of LOSEL to IF settled	d to within 2°		50		ns
RF Port Return Loss					20		dB
LO Port Return Loss		LO1/2 port selected, LO2/1 and IF terminated		22		dB	
LO FOIL NELUITI LOSS		LO1/2 port unselected, LO2/1 and IF terminated			34		UD
IF Port Return Loss		LO driven at 0dBm, RF ter differential 200 $\Omega$	rminated into $50\Omega$ ,		22		dB

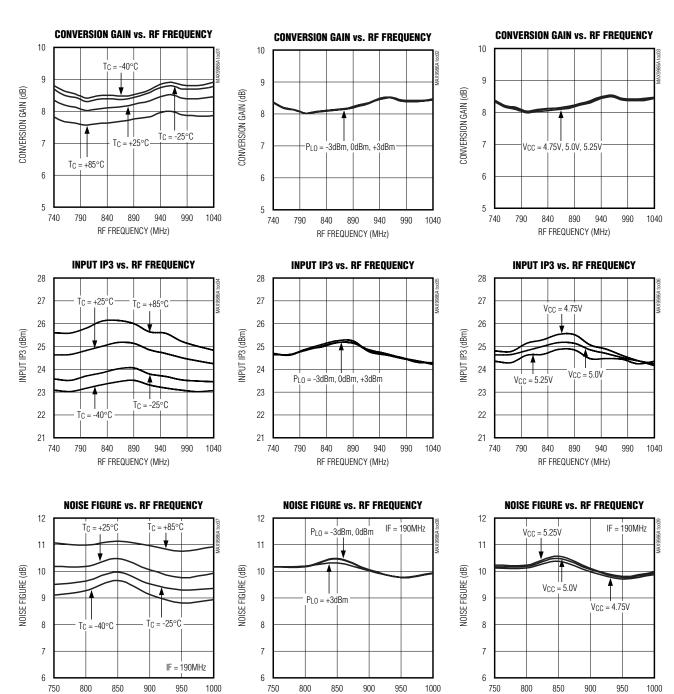
- Note 1: All limits include external component losses. Output measurements taken at IF output of the Typical Application Circuit.
- Note 2: Operation outside this range is possible, but with degraded performance of some parameters.
- Note 3: Compression point characterized. It is advisable not to operate continuously the mixer RF input above +12dBm.
- **Note 4:** Measured with external LO source noise filtered so the noise floor is -174dBm/Hz. This specification reflects the effects of all SNR degradations in the mixer, including the LO noise as defined in Maxim *Application Note 2021*.
- **Note 5:** Guaranteed by design and characterization.





### **Typical Operating Characteristics**

(MAX9986A Typical Application Circuit, VCC = +5.0V, PLO = 0dBm, PRF = -5dBm, fLO > fRF, fIF = 160MHz, unless otherwise noted.)



RF FREQUENCY (MHz)

N/IXI/N

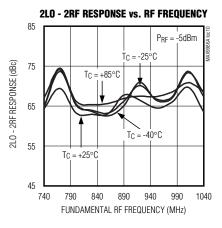
RF FREQUENCY (MHz)

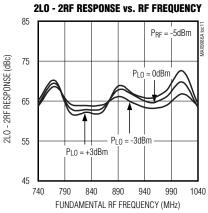
RF FREQUENCY (MHz)

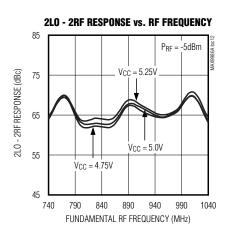


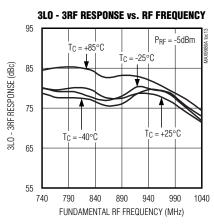
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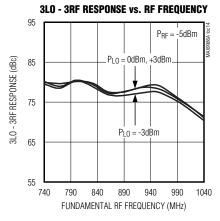
(MAX9986A Typical Application Circuit, VCC = +5.0V, PLO = 0dBm, PRF = -5dBm, fLO > fRF, fIF = 160MHz, unless otherwise noted.)

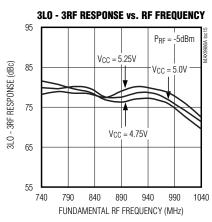


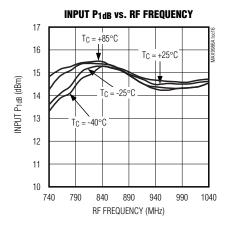


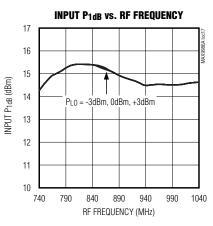


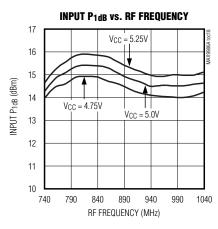








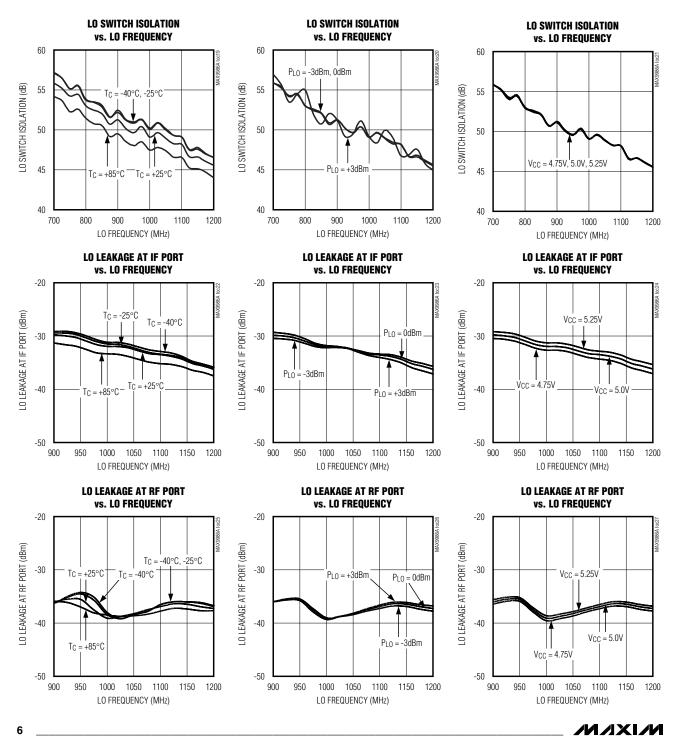






## Typical Operating Characteristics (continued)

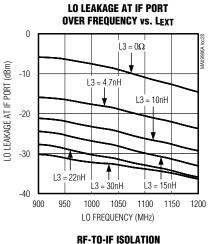
(MAX9986A Typical Application Circuit, VCC = +5.0V, PLO = 0dBm, PRF = -5dBm, fLO > fRF, fIF = 160MHz, unless otherwise noted.)

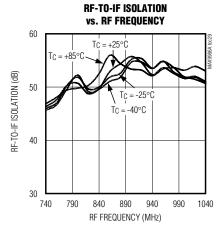


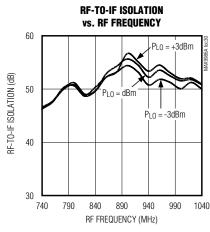


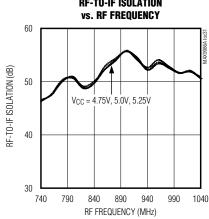
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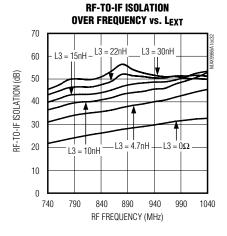
(MAX9986A Typical Application Circuit, VCC = +5.0V, PLO = 0dBm, PRF = -5dBm, fLO > fRF, fIF = 160MHz, unless otherwise noted.)

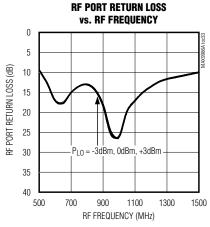


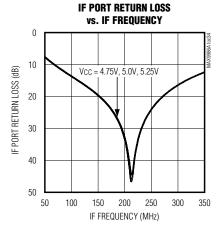


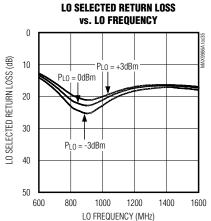








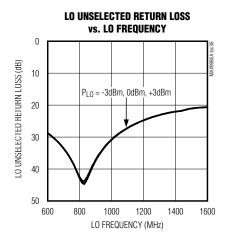


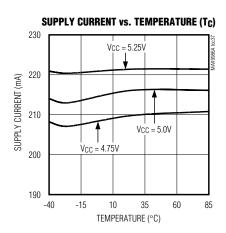




### **Typical Operating Characteristics (continued)**

(MAX9986A Typical Application Circuit, VCC = +5.0V, PLO = 0dBm, PRF = -5dBm, fLO > fRF, fIF = 160MHz, unless otherwise noted.)





### **Pin Description**

PIN	NAME	FUNCTION
1, 6, 8, 14	V <sub>CC</sub>	Power-Supply Connection. Bypass each V <sub>CC</sub> pin to GND with capacitors as shown in the <i>Typical Application Circuit</i> .
2	RF	Single-Ended $50\Omega$ RF Input. This port is internally matched and DC shorted to GND through a balun. Requires an external DC-blocking capacitor.
3	TAP	Center Tap of the Internal RF Balun. Bypass to GND with capacitors close to the IC, as shown in the <i>Typical Application Circuit</i> .
4, 5, 10, 12, 13, 17	GND	Ground
7	LOBIAS	Bias Resistor for Internal LO Buffer. Connect a $619\Omega$ ±1% resistor from LOBIAS to the power supply.
9	LOSEL	Local Oscillator Select. Logic control input for selecting LO1 or LO2.
11	LO1	Local Oscillator Input 1. Drive LOSEL low to select LO1.
15	LO2	Local Oscillator Input 2. Drive LOSEL high to select LO2.
16	LEXT	External Inductor Connection. Short LEXT to ground using a $0\Omega$ resistor. For applications requiring improved RF-to-IF and LO-to-IF isolation, connect a low-ESR inductor from LEXT to GND. See the <i>Applications Information</i> section regarding stability issues when using an LEXT inductor.
18, 19	IF-, IF+	Differential IF Outputs. Each output requires external bias to V <sub>CC</sub> through an RF choke (see the <i>Typical Application Circuit</i> ).
20	IFBIAS	IF Bias Resistor Connection for IF Amplifier. Connect a 953Ω ±1% resistor from IFBIAS to GND.
EP	GND	Exposed Ground Paddle. Solder the exposed paddle to the ground plane using multiple vias.

#### Detailed Description

The MAX9986A high-linearity downconversion mixer provides 8.2dB of conversion gain and +25dBm of IIP3, with a typical 10dB noise figure. The integrated baluns and matching circuitry allow for  $50\Omega$  single-

ended interfaces to the RF and the two LO ports. A single-pole, double-throw (SPDT) switch provides 50ns switching time between the two LO inputs with 49dB of LO-to-LO isolation. Furthermore, the integrated LO buffer provides a high drive level to the mixer core, reducing the LO drive required at the MAX9986A's

8 \_\_\_\_\_\_ /V|/X|/N



inputs to a -3dBm to +3dBm range. The IF port incorporates a differential output, which is ideal for providing enhanced IIP2 performance.

Specifications are guaranteed over broad frequency ranges to allow for use in cellular band GSM, cdma2000, iDEN, and WCDMA 2G/2.5G/3G base stations. The MAX9986A is specified to operate over a 815MHz to 1000MHz RF frequency range, a 960MHz to 1180MHz LO frequency range, and a 50MHz to 250MHz IF frequency range. Operation beyond these ranges is possible; see the *Typical Operating Characteristics* for additional details.

#### RF Input and Balun

The MAX9986A RF input is internally matched to  $50\Omega$ , requiring no external matching components. A DC-blocking capacitor is required because the input is internally DC shorted to ground through the on-chip balun.

#### LO Inputs, Buffer, and Balun

The MAX9986A is ideally suited for high-side LO injection applications with a 960MHz to 1180MHz LO frequency range. For a device with a 570MHz to 850MHz LO frequency range, refer to the MAX9984 data sheet. As an added feature, the MAX9986A includes an internal LO SPDT switch that can be used for frequencyhopping applications. The switch selects one of the two single-ended LO ports, allowing the external oscillator to settle on a particular frequency before it is switched in. LO switching time is typically less than 50ns, which is more than adequate for virtually all GSM applications. If frequency hopping is not employed, set the switch to either of the LO inputs. The switch is controlled by a digital input (LOSEL): logic-high selects LO2, logic-low selects LO1. To avoid damage to the part, voltage must be applied to VCC before digital logic is applied to LOSEL. LO1 and LO2 inputs are internally matched to  $50\Omega$ , requiring only an 82pF DCblocking capacitor.

A two-stage internal LO buffer allows a wide input power range for the LO drive. All guaranteed specifications are for an LO signal power from -3dBm to +3dBm. The on-chip low-loss balun, along with an LO buffer, drives the double-balanced mixer. All interfacing and matching components from the LO inputs to the IF outputs are integrated on-chip.

#### **High-Linearity Mixer**

The core of the MAX9986A is a double-balanced, high-performance passive mixer. Exceptional linearity is provided by the large LO swing from the on-chip LO buffer. When combined with the integrated IF amplifiers, the cascaded IIP3, 2LO - 2RF rejection, and NF performance is typically 25dBm, 69dBc, and 10dB, respectively.

#### **Differential IF Output Amplifier**

The MAX9986A mixer has a 50MHz to 250MHz IF frequency range. The differential, open-collector IF output ports require external pullup inductors to VCC. Note that these differential outputs are ideal for providing enhanced 2LO - 2RF rejection performance. Single-ended IF applications require a 4:1 balun to transform the  $200\Omega$  differential output impedance to a  $50\Omega$  single-ended output.

## **Applications Information**

#### **Input and Output Matching**

The RF and LO inputs are internally matched to  $50\Omega$ . No matching components are required. RF and LO inputs require only DC-blocking capacitors for interfacing.

The IF output impedance is  $200\Omega$  (differential). For evaluation, an external low-loss 4:1 (impedance ratio) balun transforms this impedance down to a  $50\Omega$  single-ended output (see the *Typical Application Circuit*).

#### **Bias Resistors**

Bias currents for the LO buffer and the IF amplifier are optimized by fine tuning resistors R1 and R2. If reduced current is required at the expense of performance, contact the factory for details. If the ±1% bias resistor values are not readily available, substitute standard ±5% values.

#### **LEXT Inductor**

Short LEXT to ground using a  $0\Omega$  resistor. For applications requiring improved RF-to-IF and LO-to-IF isolation, LEXT can be used by connecting a low-ESR inductor from LEXT to GND. See the *Typical Operating Characteristics* on RF-to-IF isolation and LO-to-IF leakage for various inductor values. However, the load impedance presented to the mixer must be such that any capacitance from both IF- and IF+ to ground do not exceed several picofarads to ensure stable operating conditions.

Since approximately 140mA flows through LEXT, it is important to use a low DCR wire-wound inductor.

### **Layout Considerations**

A properly designed PC board is an essential part of any RF/microwave circuit. Keep RF signal lines as short as possible to reduce losses, radiation, and inductance. For the best performance, route the ground pin traces directly to the exposed pad under the package. The PC board exposed pad **MUST** be connected to the ground plane of the PC board. It is suggested that multiple vias be used to connect this pad to the lower level ground planes. This method provides a good RF/thermal conduction path for the device. Solder the exposed pad on the bottom of the device package to the PC board. The MAX9986A Evaluation Kit can be used as a



reference for board layout. Gerber files are available upon request at www.maxim-ic.com.

#### **Power-Supply Bypassing**

Proper voltage-supply bypassing is essential for high-frequency circuit stability. Bypass each V<sub>CC</sub> pin and TAP with the capacitors shown in the *Typical Application Circuit*, see Table 1. Place the TAP bypass capacitor to ground within 100 mils of the TAP pin.

#### **Exposed Pad RF/Thermal Considerations**

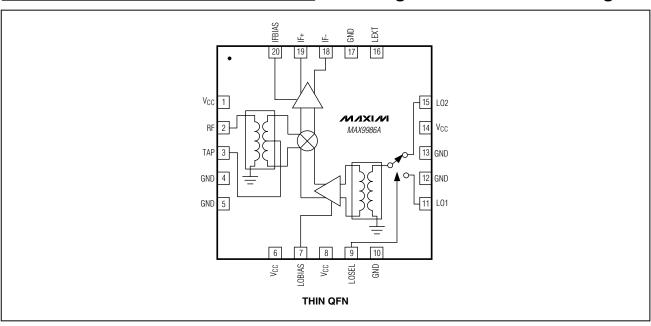
The exposed paddle (EP) of the MAX9986A's 20-pin thin QFN-EP package provides a low thermal-resistance path to the die. It is important that the PC board on which the MAX9986A is mounted be designed to conduct heat from the EP. In addition, provide the EP with a low-inductance path to electrical ground. The EP **MUST** be soldered to a ground plane on the PC board, either directly or through an array of plated via holes.

Table 1. Component List Referring to the Typical Application Circuit

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COMPONENT	VALUE	DESCRIPTION
L1, L2	330nH	Wire-wound high-Q inductors (0805)
L3*	30nH	Wire-wound high-Q inductor (0603)
C1	10pF	Microwave capacitor (0603)
C2, C4, C7, C8, C10, C11, C12	82pF	Microwave capacitors (0603)
C3, C5, C6, C9, C13, C14	0.01µF	Microwave capacitors (0603)
C15	220pF	Microwave capacitor (0402)
R1	953Ω	±1% resistor (0603)
R2	619Ω	±1% resistor (0603)
R3	0Ω	±1% resistor (1206)
T1	4:1 balun	IF balun TC4-1W-7A
U1	MAX9986A	Maxim IC

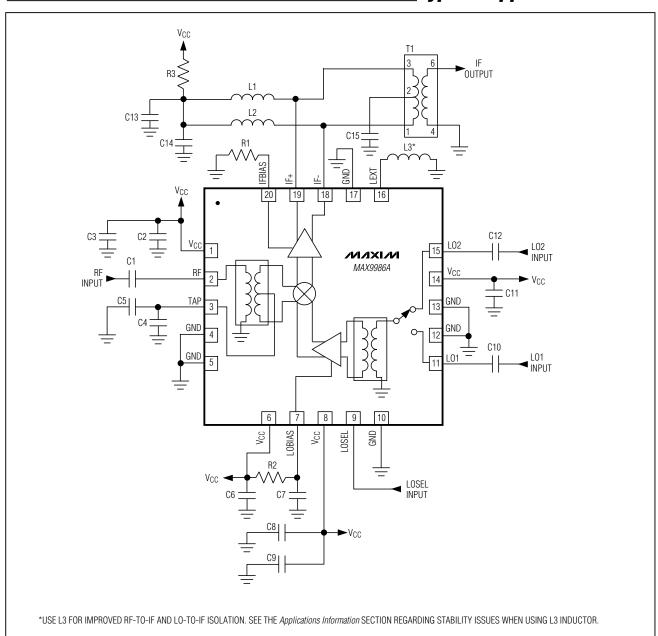
<sup>\*</sup>Use L3 for improved RF-to-IF and LO-to-IF isolation. See the Applications Information section regarding stability issues when using L3 inductor.

### Pin Configuration/Functional Diagram





## **Typical Application Circuit**



Chip Information

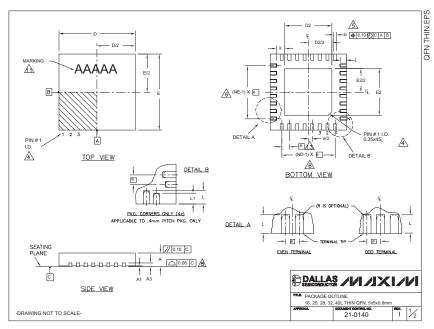
TRANSISTOR COUNT: 1017 PROCESS: SiGe BiCMOS





### **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



			С	OMM	ON I	DIMEN	SION	S										EXI	POSE	D PAC	VARI	ATION	IS.			
PKG.	1	6L 5>	:5	2	20L 5	5x5	2	8L 5	ι5	3	32L 5x5		32L 5x5 40		x5 40L		40L 5x5		PKG.		D2			E2	L	DOWN
SYMBOL	MIN.	NOM.	MAX.	MIN.	NON	I. MAX.	MIN.	NOM.	MAX.	MIN.	IN. NOM. MAX. MI		MIN.	NOM.	MAX.		CODES	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	-0.15	BONDS ALLOWED	
Α	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80		T1655-2	3.00	3.10	3.20	3.00	3.10	3.20	**	YES	
A1	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05		T1655-3	3.00	3.10	3.20	3.00	3.10	3.20	**	NO	
A3	0.	20 RE	F.	0.	20 F	EF.	0.	20 RE	F.	0.	20 RE	F.	0.	20 RE	F.		T1655N-1	3.00	3.10	3.20	3.00	3.10	3.20	**	NO	
b						0.35											T2055-3	3.00	3.10	3.20	3.00	3.10	3.20	**	YES	
D	4.90			4.90			4.90	5.00		4.90	5.00			5.00			T2055-4	3.00	3.10	3.20	3.00	3.10	3.20	**	NO	
E	4.90			_	_	_	4.90				5.00		_	5.00	_		T2055-5	3.15	3.25	3.35	3.15	3.25	3.35	0.40	YES	
e		80 B			.65 E		-	.50 B	SC.		.50 BS			.40 B			T2855-3	3.15	3.25		3.15	3.25	3.35	**	YES	
k L	0.25		- 0.50	0.25	_	- 0.05	0.25		- 0.05	0.25	- 10	- 0.50	_	0.35	_		T2855-4	2.60	2.70	2.80	2.60	2.70	2.80	**	YES	
L1	0.30	0.40	0.50	0.45	U.5	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.40	0.50	_		T2855-5	2.60	2.70	2.80	2.60	2.70	2.80	**	NO	
N	-	16	٠.	-	20	1 -	-	28	-	-	32	-	0.30	40	0.50		T2855-6	3.15	3.25	3.35	3.15	3.25	3.35	**	NO	
ND.		4			5			7			8			10			T2855-7	2.60	2.70	2.80	2.60	2.70	2.80	**	YES	
NE		4			5			7			8			10			T2855-8	3.15	3.25	3.35	3.15	3.25	3.35	0.40	YES	
JEDEC	1	WHH	3		WHE	IC .	١	VHHC	)-1	٧	VHHD	-2					T2855N-1	3.15	3.25	3.35	3.15	3.25	3.35	**	NO	
																	T3255-3	3.00	3.10	3.20	3.00	3.10	3.20	**	YES	
IOTES:																	T3255-4	3.00	3.10	3.20	3.00	3.10	3.20	**	NO	
1. DIM	IENSI	ONING	8 TC	DLER/	ANCI	NG CO	NFOR	км то	ASM	E Y14	.5M-1	994.					T3255-5	3.00	3.10	3.20	3.00	3.10	3.20	**	YES	
2. ALL	DIME	NSIO	NS AF	RE IN	MILI	IMETE	RS A	NGI F	SARE	= IN D	FGRE	FS					T3255N-1	3.00	3.10	3.20	3.00	3.10	3.20	**	NO	
3 N IS																	T4055-1	3.20	3.30	3.40	3.20	3.30	3.40	**	YES	
OPT IDE DIM	NFORI FIONA NTIFIE IENSIO	M TO L, BU ER MA	JESD T MUS XY BE APPLII	95-1 ST BE EITHI ES TO	SPP- LOC ER A	AND TO 012. E ATED MOLD TALLIZ ERMIN	ETAI WITH OR N	S OF IN TH IARKE	TERME ZON	MINAL NE INI ATUF	#1 ID DICAT RE.	ENTI ED. T	FIER A	ARE RMIN	IAL#1							OLL 00	J. W.	DIMERSO	IONS TABLE	
A ND												) ANE	ESI	DE RE	SPEC	TIVE	LY.									
A. cor												WEI	1 49 1	TUE T	EDMIN	IAI C										
9. DR/																inlo										
T28	55-3 A	ND T	2855-	6.				EXCE	PIE	KPU5	ED PA	ווט טוו	MENS	ION F	UR			Г								
						D 0.10													ĐΦ	ALL	_AS		41 1			
11. MA																			I 8E	MICOND	UCTOR	AF 107				
12. NUI LEA						RE FO						BASI	C DIN	IENSI	ON "e'	, -0.0	05.	ı			SE OUT		N OFN	5x5x0.8	Rmm	
																		_ L								
RAWING																			APPROVAL		∞		0HTROL NO.		REEV. 2	

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